

Special Issue

VR/AR/MR with Cloud Computing

Message from the Guest Editors

With more online and mobile user activity, the demand for immersive virtual/augmented reality services is increasing. Virtual reality, augmented reality, and mixed reality have been continuously developed as they come to market for devices, software, and content.

This Special Issue, entitled “VR/AR/MR with Cloud Computing,” invites manuscripts focused on research regarding content, platforms, networks, and devices. Experimental, theoretical, and computational research on the VR/AR/MR concepts are all encouraged.

Topics include, but are not limited to:

- VR/AR/MR Content acquisitions
- VR/AR/MR Cloud computing applications
- VR/AR/MR Devices and platforms

Guest Editors

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Deadline for manuscript submissions

closed (10 August 2021)



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About the Journal

Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal *Applied Sciences* has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

Editor-in-Chief

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